Metal Foil Current Sense Resistors, Low Value (Down to 0.001 Ω)

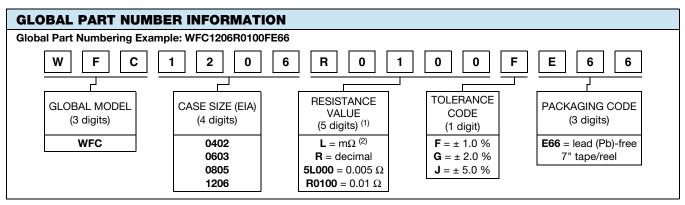


- Ultra low sensing resistance
- Low TCR (down to 50 ppm/°C)
- Chip size down to 0402, minimizing board space
- Sulfur resistant
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Switching power supply
- Voltage regulation module
- DC/DC converter, adaptor, battery pack, charger
- Pad and cell phone
- Power management

STANDARD ELECTRICAL SPECIFICATIONS								
GLOBAL MODEL	SIZE	POWER RATING W	TOLERANCE %	RESISTANCE VALUE RANGE Ω	WEIGHT (typical) g/1000 pieces			
WFC0402	0402	0.125	± 1, ± 2, ± 5	0.003 to 0.05	1.1			
WFC0603	0603	0.33	± 1, ± 2, ± 5	0.001 to 0.005	3.3			
	0603	0.25	± 1, ± 2, ± 5	0.0051 to 0.03	3.3			
WFC0805	0805	0.50	± 1, ± 2, ± 5	0.001 to 0.04	6.8			
WFC1206	1206	1.0	± 1, ± 2, ± 5	0.001 to 0.05	17.4			
	1206	0.5	± 1, ± 2, ± 5	0.100 to 0.18	17.4			



Notes

⁽¹⁾ Resistance values are available per E12 and E24 decades; <u>www.vishay.com/doc?28372</u>

⁽²⁾ Use "L" for resistance values < 0.01 Ω

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COMPLIANT HALOGEN

FREE GREEN

(5-2008)

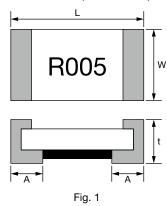


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TECHNICAL SPECIFICATIONS								
DADAMETED	LINUT	RESISTOR CHARACTERISTICS						
PARAMETER	UNIT	WFC0402	WFC0603	WFC0805	WFC1206			
	ppm/°C	-	± 100 for 1 mΩ to 5 mΩ	-	-			
Temperature coefficient		± 150 for 3 mΩ to 7 mΩ	± 150 for 5.1 mΩ to 9 mΩ	± 100 for 1 mΩ to 10 mΩ	± 100 for 1 mΩ to 10 mΩ			
		\pm 100 for 8 m Ω to 50 m Ω	\pm 75 for 10 m Ω to 30 m Ω	± 50 for 10.1 mΩ to 40 mΩ	\pm 50 for 10.1 m Ω to 180 m Ω			
Operating temperature range	°C	-55 to +170						
Maximum working voltage	V	$(P \times R)^{1/2}$						
Maximum element temperature	°C	170						

DIMENSIONS in inches (millimeters)



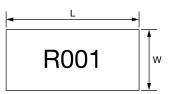




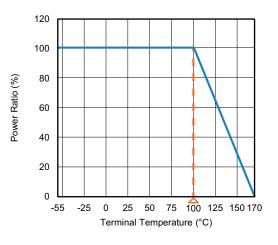
Fig. 2

TYPE	RESISTANCE		DIMENSIONS FIG.				
(INCH SIZE)	RANGE (mΩ)	L	L W t		Α	Binenoiono Fia.	
WFC0402	3 to 7		0.55 . 0.10	0.45 ± 0.10	0.35 ± 0.10	1	
VVFC0402	7.1 to 50	1.00 ± 0.10	0.55 ± 0.10	0.45 ± 0.10	0.25 ± 0.10	1	
WFC0603	1 to 5	1.60 ± 0.10	0.95 ± 0.25	0.60 ± 0.25	0.55 ± 0.20	2	
	5.1 to 30	1.00 ± 0.10	0.80 ± 0.10	0.55 ± 0.15	0.30 ± 0.20	1	
WFC0805	1 to 5	2.10 ± 0.20	1.40 ± 0.20	0.60 max.	0.60 ± 0.20	2	
WFC0805	5.1 to 40	2.00 ± 0.20	1.30 ± 0.15	0.70 ± 0.15	0.45 ± 0.20	1	
WFC1206	1 to 3	3.10 ± 0.20	3.10 ± 0.20 1.55 ± 0.20	0.75 ± 0.25	1.30 ± 0.20	2	
	3.1 to 180	3.10 ± 0.20		0.80 ± 0.15	0.55 ± 0.20	1	

Note

• 0402 has no marking; 0603, 0805, 1206 marking shows two digits for resistance

DERATING



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PERFORMANCES

ENV	ENVIRONMENTAL PERFORMANCE							
NO.	ITEM	TEST CONDITION	SPECIFICATION					
1	Short time overload	5 times rated power for 5 seconds (JIS-C5202-5.5)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$					
2	Temperature coefficient of resistance (TCR)	+25 °C / +125 °C (JIS-C5202-5.2) TCR (ppm/°C) = $\frac{\Delta R}{R \times \Delta t} \times 10^{6}$	Refer to Electrical Specification					
3	Damp heat with load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90 % to 95 % and a temperature of 40 °C \pm 2 °C for the period of 1000 hours with applying rated power 1.5 hours ON and 0.5 hour OFF. (MIL-STD-202, method 103)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$					
4	High temperature exposure	The chip (mounted on board) is exposed in the heat chamber 125 °C \pm 3 °C for 1000 hours. (JIS-C5202-7.2)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$					
5	Load life	Apply rated power at 70 °C \pm 2 °C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$					
6	Rapid change of temperature	The chip (mounted on board) is exposed, -55 °C \pm 3 °C (30 min.) / +155 °C \pm 2 °C (30 min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature +155 (\pm 2) °C +25 (\pm 2) °C -55 (\pm 3) °C 1 cycle	Δ <i>R</i> : ± (1 % + 0.0005 Ω)					

FUN	FUNCTION PERFORMANCE							
NO.	ITEM	TEST CONDITION	SPECIFICATION					
1	Bending strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2 mm (+0.2 / -0 mm) illustrated in the figure below and hold for 10 s \pm 1 s. (JIS-C5202-6.1) Position before bend Unit: mm Position before bend Amount of bend Testing printed circuit board	Δ <i>R</i> : ± (1 % + 0.0005 Ω)					
2	Solvent resistance	Complete immersion of specimens in isopropyl alcohol for 3 (+5, -0) min. 25 °C \pm 5 °C. (MIL-STD-202, method 215)	Verify marking permanency. (not required for laser etched parts or parts with no marking)					
3	Resistance to solder heat	The specimen chip shall be immersed into the flux specified in the solder bath 260 °C \pm 5 °C for 10 s \pm 1 s. (MIL-STD-202, method 210)	Δ <i>R</i> : ± (1 % + 0.0005 Ω)					



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NO.	ITEM	ITEM TEST CONDITION				
4	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath 235 °C ± 5 °C for 2 s ± 0.5 s. It shall be immersed to a point 10 mm from its root. (Sn96.5 / Ag3.0 / Cu0.5) (JIS-C5 202-6.11) Molten solder SMD Molten solder H = 10 mm H = 10 mm min.	Solder shall be covered 95 % or more of the electrode area			

Notes

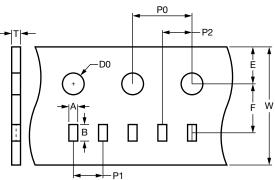
- 0.5 W with total solder pad trace size of 100 mm². The surface temperature of component should below 100 °C ٠
- 1.0 W with total solder pad trace size of 100 mm². The surface temperature of component should below 100 °C ٠

TAPE PACKAGING SPECIFICATIONS							
MODEL	REEL						
MODEL	TAPE WIDTH	DIAMETER	PIECES/REEL				
WFC0402	Embossed paper tape	178 mm / 7"	10 000				
WFC0603, WFC0805, WFC1206	Embossed paper tape	178 mm / 7"	5000				

Note

٠ Embossed carrier tape per EIA (EIAJ)

PAPER TAPE SPECIFICATIONS



ТҮРЕ	RESISTANCE	CARRIER DIMENSIONS (in millimeters)									
	RANGE	Α	В	E	F	w	P0	P1	P2	D0	Т
WFC0402	3 m Ω to 50 m Ω	0.7 ± 0.05	1.2 ± 0.05	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	2.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.6 ± 0.1
WFC0603	1 m Ω to 5 m Ω	1.4 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.75 ± 0.1
WFC0603	5.1 m Ω to 30 m Ω	1.1 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.70 ± 0.1
WFC0805	1 m Ω to 5 m Ω	2.4 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.75 ± 0.1
WFC0805	5.1 m Ω to 40 m Ω	1.6 ± 0.1	2.4 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.97 ± 0.1
WFC1206	1 m Ω to 3 m Ω	2.0 ± 0.1	3.6 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.87 ± 0.1
WFC1206	3.1 m Ω to 180 m Ω	2.0 ± 0.1	3.6 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.97 ± 0.1

Notes

Embossed carrier tape per EIA (EIAJ)

Additional packaging details at www.vishay.com/doc?20051

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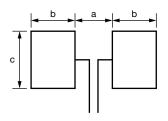
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STORAGE CONDITIONS

Temperature: 5 °C to 35 °C, humidity: 40 % to 75 %

RECOMMENDED SOLDER PAD LAYOUT



ТҮРЕ	PAD LAYOUT DIMENSIONS (in millimeters)						
ITFE	а	b	С				
0402 (3 mΩ to 7 mΩ)	0.30	0.60	0.60				
0402 (7.1 mΩ to 50 mΩ)	0.50	0.50	0.60				
0603 (1 mΩ to 5 mΩ)	0.30	1.10	1.50				
0603 (5.1 mΩ to 9 mΩ)	0.60	0.90	1.00				
0603 (9.1 mΩ to 30 mΩ)	0.90	0.70	1.00				
0805 (1 mΩ to 5 mΩ)	0.80	1.60	1.45				
0805 (5.1 mΩ to 40 mΩ)	1.20	1.20	1.40				
1206 (1 mΩ to 3 mΩ)	0.40	1.80	2.20				
1206 (3.1 m Ω to 180 m Ω)	2.20	1.30	1.80				

Note

• Recommend to use the steel plate which thickness > 100 µm to avoid the insufficient solder height

SOLDERING RECOMMENDATIONS

- Peak reflow temperatures and durations:
 - IR reflow peak = 260 °C max. for 10 s
 - Wave solder = 260 °C max. for 10 s
- · Compatible with lead and lead (Pb)-free solder reflow processes
- Recommended IR reflow profile for surface mount devices: <u>www.vishay.com/doc?31052</u>



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